

2222 Wellington Court Lisle, IL 60532 USA

# **Product Compliance Declaration**

Please see <u>www.molex.com</u> for the most up-to-date information.

Contact Information						
Name	Molex Product Compliance	E-Mail	Product.Compliance@molex.com			
Part Inform	ation					
Part Number	0533980471	Part Weight	0.170799G			
Part Name	PicoBlade 1.25 SMT ST PKG 4P					

## **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
PicoBlade 1.25 SMT ST PKG 4P	Assembly		100	0.170799
1.25 W/B Wafer Assy For SMT ST 4Ckt	Assembly		100	0.170799
Fitting Nail Chain W/Plt	Assembly		17.3256	0.029592
FITTING NAIL FOR 53261	Component		16.979	0.029
Phosphor Bronze 5% Unplated	Material		16.979	0.029
Copper	Substance	7440-50-8	16.1046	0.027507
Tin	Substance	7440-31-5	0.849	0.00145
Phosphorus	Substance	7723-14-0	0.0255	0.000044
Tin Plating	Material		0.1733	0.000296
Tin	Substance	7440-31-5	0.1733	0.000296
Nickel Plating	Material		0.1733	0.000296
Nickel	Substance	7440-02-0	0.1733	0.000296
1.25 W/B SOLDER PIN	Component		29.3955	0.050207

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Tin Plating	Material		0.0023	0.000004
Tin	Substance	7440-31-5	0.0023	0.000004
1.25 W/B SOLDER PIN	Component		28.8058	0.0492
Phosphor Bronze 5% Unplated	Material		28.8058	0.0492
Copper	Substance	7440-50-8	27.3223	0.046666
Tin	Substance	7440-31-5	1.4403	0.00246
Phosphorus	Substance	7723-14-0	0.0432	0.000074
Nickel Plating	Material		0.0023	0.000004
Nickel	Substance	7440-02-0	0.0023	0.000004
Sealing Surface Treatment	Material		0.585	0.000999
Poly(oxy-1,2-ethanediyl), alpha-tridecyl-omega- hydroxy	Substance	24938-91-8	0.5844	0.000998
Misc.	Substance	system	0.0006	1E-06
1.25 WtB SMT Str Wafer 4Ckt	Component		53.2789	0.091
PA46 GF30 NATURAL	Material		53.2789	0.091
PA46	Substance		21.5513	0.03681
GF-Fibre	Substance		16.2501	0.027755
Flame Retardant, ISO 1043-4 FR(17)	Substance		11.7214	0.02002
Antimonytrioxide	Substance	1309-64-4	3.1967	0.00546
Further Additives, not to declare	Substance	system	0.5594	0.000956

## **ROHS** Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

**Contained Substances Exceeding Threshold** 

None

Exemptions

None

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# **REACH-SVHC** Declaration Information

Regulatory Revision D(2022)4187-DC (10 June 2022)

#### **Contained Substances Exceeding Threshold**

None

## **GADSL** Declaration Information

Regulatory Revision GADSL imported from IMDS

#### **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
Lead	Phosphor Bronze 5% A (CA510)	*Note	250	Yes
Antimonytrioxide	PA46 GF30 NATURAL	*Note	60,000	Yes
nickel	Ep-Ni	*Note	997,500	Yes
Copper	Phosphor Bronze 5% A (CA510)	*Note	943,350	Yes

\*Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

#### Exemptions

Part Name	Exemption
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
Phosphor Bronze 5% A (CA510)	44 Concentration within acceptable GADSL limits
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/ cm2/week)

# **HFLH Declaration Information**

Regulatory Revision IEC 61249-2-21

#### **Contained Substances Exceeding Threshold**

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Bromine and its compounds	PA46 GF30 NATURAL	900	220,000	Yes
Bromine and Chlorine combined	PA46 GF30 NATURAL	1,500	220,000	Yes

# **China ROHS Declaration Information**

Part Number 0533980471							
Part Name PicoBlade 1.25 SMT ST PKG 4P							
Part Information			Haz	ardous S	Substance	s	
Components	L	.ead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
PicoBlade 1.25 SMT ST PKG 4P		0	0	0	0	0	0
1.25 W/B Wafer Assy For SMT ST 4Ckt		0	0	0	0	0	0
Fitting Nail Chain W/Plt		0	0	0	0	0	0
FITTING NAIL FOR 53261		0	0	0	0	0	0
1.25 W/B SOLDER PIN		0	0	0	0	0	0
1.25 W/B SOLDER PIN		0	0	0	0	0	0
1.25 WtB SMT Str Wafer 4Ckt		0	0	0	0	0	0

# **Additional Information**

Annex XVII to REACH (76/769/EEC)	Compliant
Regulation (EU) 2019/1021 (POP)	Compliant

# **Process Information**

Component Plating / Surface Finish	MSn
Termination Base Alloy	P-Bronze
Solder Alloy	N/A
Process Capability	REFLOW
Maximum Exposure Time (seconds)	060

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Maximum Process Temperature (C)	250
Maximum Cycles at Reflow Temperature	002
J-STD-020 Moisture Sensitivity Level	N/A

Aug 16, 2022

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